

04R-00315-1.0

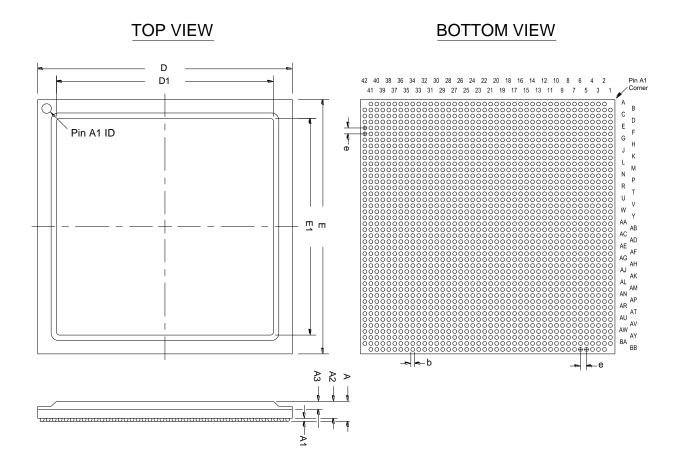
## 1760-Pin FineLine Ball-Grid Array (FBGA) - Flip Chip - Single-Piece Lid - A:3.50 - D1:36.2

- All dimensions and tolerances conform to ASME Y14.5M 1994.
- Controlling dimension is in millimeters.
- Pin A1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Package Information			
Description	Specification		
Ordering Code Reference	F		
Package Acronym	FBGA		
Substrate Material	BT		
Solder ball composition	Regular: 63Sn:37Pb (Typ.) Pb-free: Sn:3Ag:0.5Cu (Typ.)		
JEDEC Outline Reference	MS-034 Variation: AAV-1		
Lead Coplanarity	0.010 inch (0.25 mm)		
Weight	17.8 g (Typ.)		
Moisture Sensitivity Level	Printed on moisture barrier bag		

Symbol —	Millimeters			
	Min.	Nom.	Max.	
А	3.10	3.30	3.50	
A1	0.40	0.50	0.60	
A2	2.50	2.80	3.10	
A3	1.30	1.40	1.50	
D	42.50 BSC			
D1	36.20 BSC			
E	42.50 BSC			
E1	36.20 BSC			
b	0.50	0.60	0.70	
е	1.00 BSC			

## Package Outline



## **Document Revision History**

Table 1 shows the revision history for this document.

## Table 1. Document Revision History

Date	Version	Changes
May 2011	1.0	Initial release



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